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## VOLTAGE RANGE 20 to 100 Volts CURRENT 5.0 Ampere



#### **FEATURES**

- \* Ideal for surface mount applications
- \* Easy pick and place
- \* Built-in strain relief
- \* Low forward voltage drop

#### **MECHANICAL DATA**

- \* Case: Molded plastic
- \* Epoxy: UL 94V-0 rate flame retardant
- \* Metallurgically bonded construction
- \* Polarity: Color band denotes cathode end
- \* Mounting position: Any

## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwies specified. Single phase half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

P/N(MARK)	SS52F	SS53F	SS54F	SS55F	SS56F	SS58F	SS59F	SS510F	UNITS
Maximum Recurrent Peak Reverse Voltage	20	30	40	50	60	80	90	100	V
Maximum RMS Voltage		21	28	35	42	56	63	70	V
Maximum DC Blocking Voltage	20	30	40	50	60	80	90	100	V
Maximum Average Forward Rectified Current							•		
At T∟=100°C		5.0				Α			
Peak Forward Surge Current, 8.3 ms single half sine-wave									
superimposed on rated load (JEDEC method)		120							Α
Maximum Instantaneous Forward Voltage at 5.0A		0.55		0.70		0.85		V	
Maximum DC Reverse Current Ta=25°C		0.1 0.02				mA			
at Rated DC Blocking Voltage Ta=100°C		5 2				mA			
Typical Junction Capacitance (Note1)		380				pF			
Typical Thermal Resistance R JL (Note 2)		10			°C/W				
Operating Temperature Range T <sub>J</sub>		-65 —+150			°C				
Storage Temperature Range Tsтg		-65 — +150				°C			

#### NOTES

- 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
- 2. Thermal Resistance Junction to Lead.



#### RATING AND CHARACTERISTIC CURVES (SS52F THRU SS510F)

#### FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

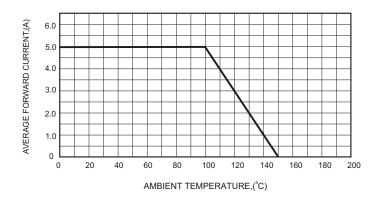


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

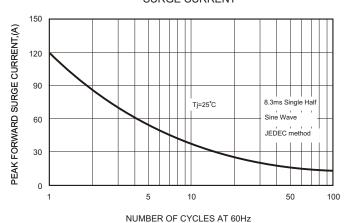


FIG.4-TYPICAL JUNCTION CAPACITANCE

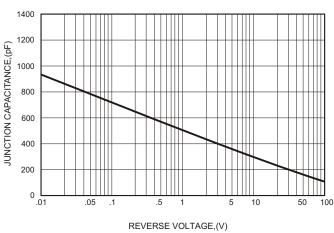


FIG.2-TYPICAL FORWARD

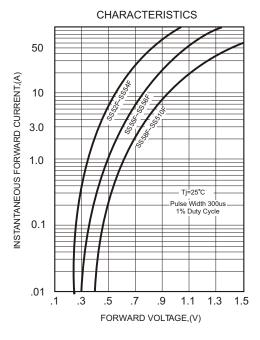
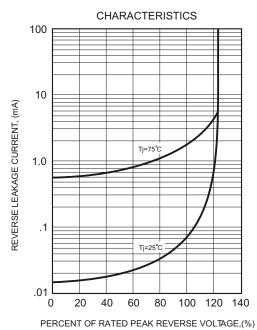
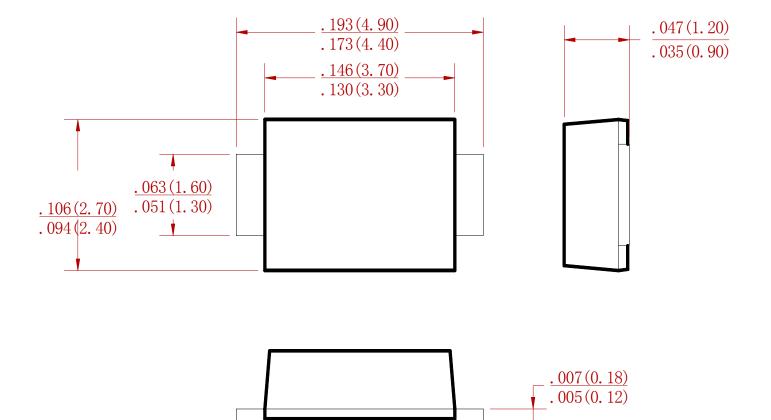


FIG.5 - TYPICAL REVERSE





#### **PACKAGE MECHANICAL DATA**



Dimensions in inches and (millimeters)

- . 051 (1. 30) . 031 (0. 80)

#### **REEL SPECIFICATION**

P/N	PKG	QTY
SS52F THRU SS510F	SMAF	3000



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